

REMARKS

Claims 2 and 4-21 are all the claims pending in the application.

I. The Rejections Under 35 U.S.C. §103(a)

Claims 1, 3, 4, 8-10, and 12-20 are rejected under 35 U.S.C. §103(a) as allegedly being unpatentable over Iwasa et al in view of Kobayashi et al.

Claims 5 and 11 are rejected under 35 U.S.C. §103(a) as allegedly being unpatentable over Iwasa et al in view of Kobayashi et al further in view of Tan et al.

Claims 1-20 are rejected under 35 U.S.C. §103(a) as allegedly being unpatentable over Tan et al in view of Kobayashi et al.

In Paragraph 6 of the Office Action, the Examiner states that the subject matter of claim 21 is allowable. Applicants have amended claim 21 to be in independent form and have canceled claims 1 and 3, without prejudice or disclaimer. Additionally, claims 2, 4, 5 and 8-20 have been amended to be dependent on claim 21. In view thereof, Applicants respectfully submit that the rejections based on Iwasa et al in view of Kobayashi et al, Iwasa et al in view of Kobayashi et al further in view of Tan et al and Tan et al in view of Kobayashi et al are moot.

For the above reasons, it is respectfully submitted that the subject matter of claims 2 and 4-21 is neither taught by nor made obvious from the disclosures of Iwasa et al in view of Kobayashi et al, Iwasa et al in view of Kobayashi et al and Tan et al and Tan et al in view of Kobayashi et al and it is requested that the rejection under 35 U.S.C. §103(a) be reconsidered and withdrawn.

II. Conclusion

In view of the above, Applicants respectfully submit that their claimed invention is allowable and ask that the rejections under 35 U.S.C. §103 be reconsidered and withdrawn. Applicants respectfully submit that this case is in condition for allowance and allowance is respectfully solicited.


If any points remain at issue which the Examiner feels may be best resolved through a personal or telephone interview, the Examiner is kindly requested to contact the undersigned at the local exchange number listed below.

Applicants hereby petition for any extension of time which may be required to maintain the pendency of this case. The USPTO is directed and authorized to

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charge all required fees, except for the Issue Fee and the Publication Fee, to Deposit
Account No. 19-4880. Please also credit any overpayments to said Deposit Account.

Respectfully submitted,



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PATENT TRADEMARK OFFICE

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APPENDIX
VERSION WITH MARKINGS TO SHOW CHANGES MADE

IN THE CLAIMS:

Claims 1 and 3 are canceled.

The claims are amended as follows:

2 (Twice Amended). The positive-working radiation-sensitive composition according to claim [1] 21, wherein said resin (a) comprises repeating units, each containing a hydroxystyrene group, wherein at least a part of the hydroxy groups of the hydroxystyrene groups of the repeating units are protected by said acid-decomposing group of formula (I).

4 (Amended). The positive-working radiation-sensitive composition according to claim [1] 21, wherein the compound (b-1) is a compound generating a sulfonic acid by the irradiation of an active light or radiation and the compound (b-2) is a compound generating a carboxylic acid by the irradiation of an active light or radiation.

5 (Amended). The positive-working radiation-sensitive composition according to claim [1] 21, wherein the composition further contains an organic basic compound.

8 (Amended). The positive-working radiation-sensitive composition according to claim [1] 21, wherein the amount of the resin (a) is from 10 to 99.9% by weight based on the total weight excluding a solvent of the composition.

9 (Amended). The positive-working radiation-sensitive composition according to claim [1] 21, wherein the amount of the resin (a) is from 50 to 99.5% by weight based on the total weight excluding a solvent of the composition.

10 (Amended). The positive-working radiation-sensitive composition according to claim [1] 21, wherein the amount of the resin (a) is from 70 to 99.0% by weight based on the total weight of the composition excluding the solvent.

11 (Twice Amended). The positive-working radiation-sensitive composition according to claim [1] 21, wherein the composition further contains an alkali-soluble resin which does not contain an acid-decomposing group.

12 (Amended). The positive-working radiation-sensitive composition according to claim [1] 21, wherein the amount of the component (b-1) is from 0.001 to 40% by weight based on the total weight of the composition excluding the solvent.

13 (Amended). The positive-working radiation-sensitive composition according to claim [1] 21, wherein the amount of the component (b-1) is from 0.01 to 20% by weight based on the total weight of the composition excluding the solvent.

14 (Amended). The positive-working radiation-sensitive composition according to claim [1] 21, wherein the amount of the component (b-1) is from 0.1 to 5% by weight based on the total weight of the composition excluding the solvent.

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15 (Amended). The positive-working radiation-sensitive composition according to claim [1] 21, wherein the amount of the component (b-2) is from 0.1 to 20% by weight based on the total weight of the composition excluding the solvent.

16 (Amended). The positive-working radiation-sensitive composition according to claim [1] 21, wherein the amount of the component (b-2) is from 0.5 to 10% by weight based on the total weight of the composition excluding the solvent.

17 (Amended). The positive-working radiation-sensitive composition according to claim [1] 21, wherein the amount of the component (b-2) is from 1 to 7% by weight based on the total weight of the composition excluding the solvent.

18 (Amended). The positive-working radiation-sensitive composition according to claim [1] 21, wherein the weight ratio of the components (b-2)/(b-1) is from 0.01 to 5.

19 (Amended). The positive-working radiation-sensitive composition according to claim [1] 21, wherein the weight ratio of the components (b-2)/(b-1) is from 0.05 to 3.

20 (Amended). The positive-working radiation-sensitive composition according to claim [1] 21, wherein the weight ratio of the components (b-2)/(b-1) is from 0.1 to 2.

21 (Amended). [The] A positive-working radiation-sensitive composition [according to claim 1, wherein the resin (a) is a resin having an acid-decomposing

group represented by the following formula (I'), which is decomposed by the action of an acid to increase the solubility in an alkali developer:] comprising

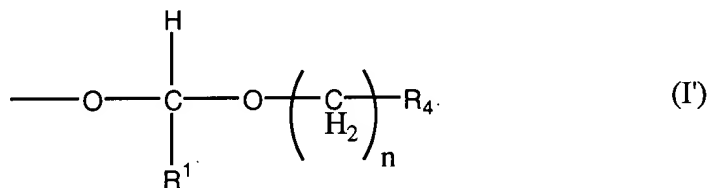
(a) a resin having an acid-decomposing group represented by the following formula (I'), which is decomposed by the action of an acid to increase the solubility in an alkali developer,

(b-1) at least one compound which generates an acid by the irradiation of an active light or radiation and contributes to the decomposition reaction of the above-described acid-decomposing group,

(b-2) at least one compound which generates an acid by the irradiation of an active light or radiation but does not contribute to the decomposition reaction of the above-described acid-decomposing group,

(c) a surface active agent, and

(d) a solvent,



wherein R₁ represents an alkyl group having from 1 to 4 carbon atoms, R₄ represents a substituted or unsubstituted aryl group or a substituted or

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unsubstituted cyclic alkyl group having from 3 to 15 carbon atoms; n represents a natural number of from 1 to 4.